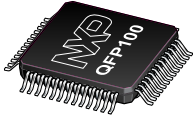


# SOT2045-1

PQFP-E-100; plastic quad flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

22 August 2023

Package information



## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HDQFP100
<b>Package type industry code</b>	PQFP-E-100
<b>Package style descriptive code</b>	QFP (quad flat package)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-355 C
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	30-05-2023
<b>Manufacturer package code</b>	98ASA01570D

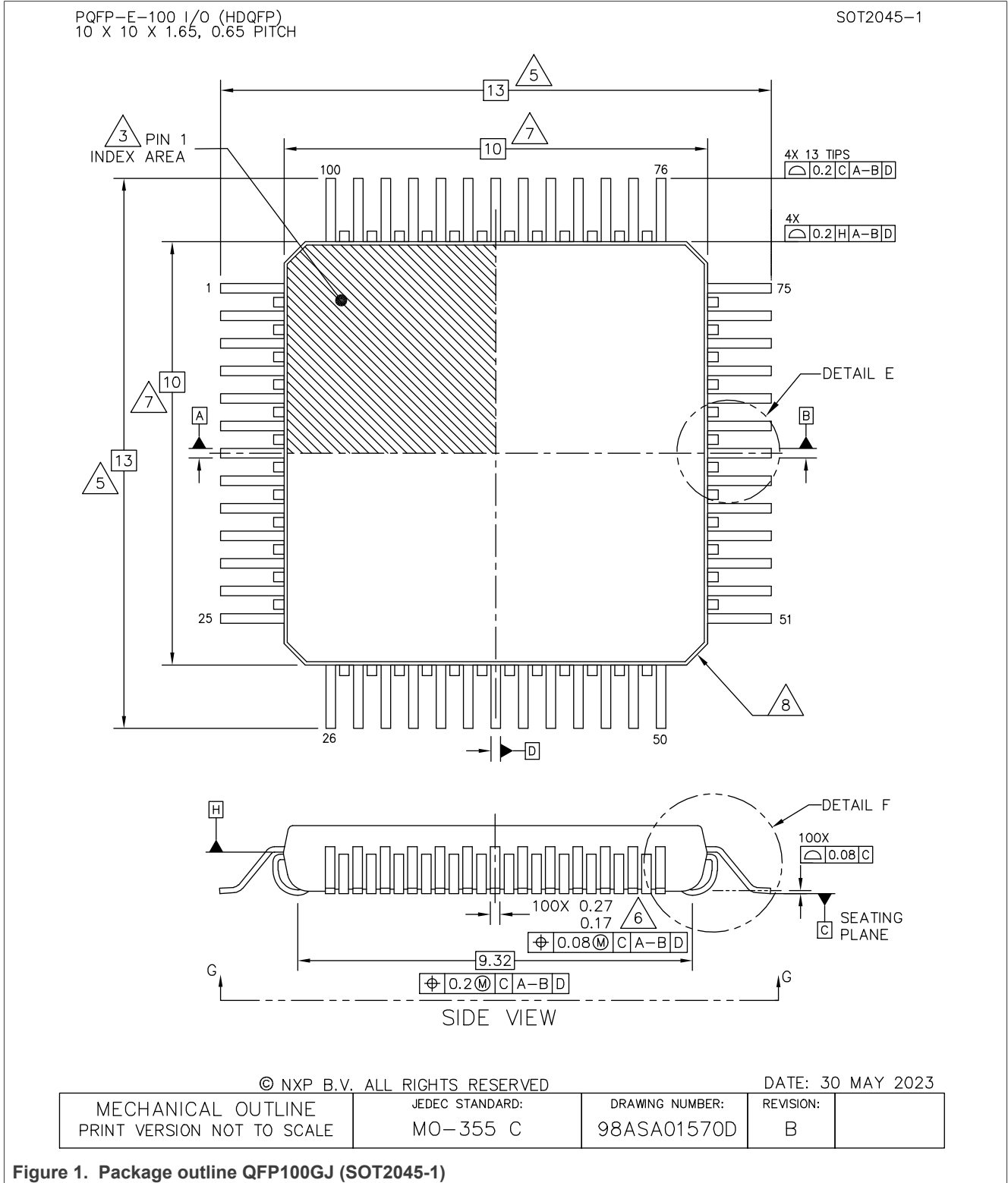
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	10	-	mm
package width	-	10	-	mm
seated height	-	1.65	1.75	mm
package height	1.5	1.55	1.6	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	100	-	



PQFP-E-100; plastic qual flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

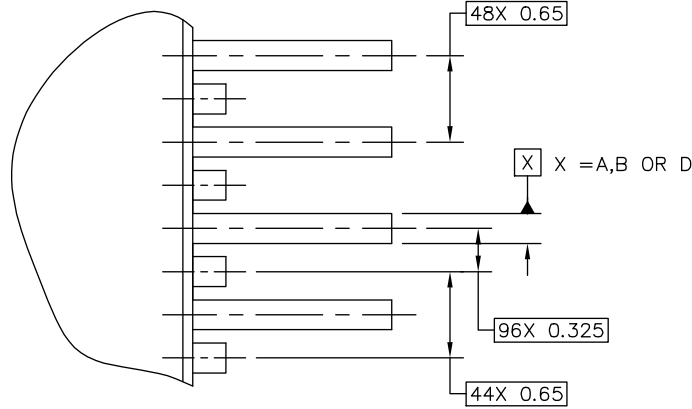
2 Package outline



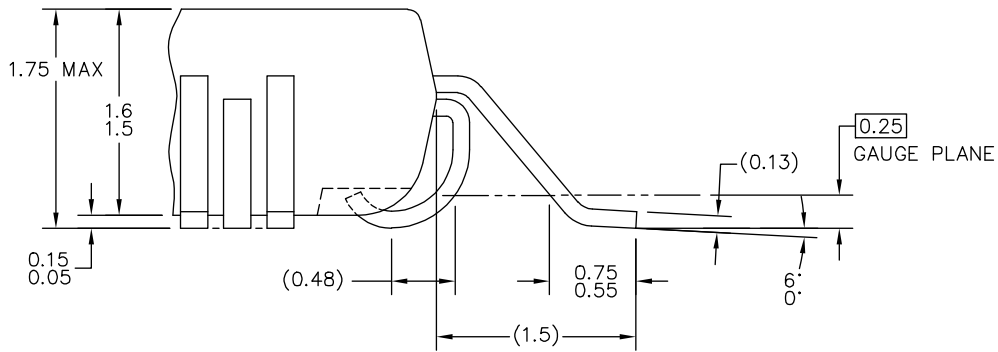
PQFP-E-100; plastic qual flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

PQFP-E-100 I/O (HDQFP)  
10 X 10 X 1.65, 0.65 PITCH

SOT2045-1



DETAIL E



DETAIL F

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DATE: 30 MAY 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	JEDEC STANDARD: MO-355 C	DRAWING NUMBER: 98ASA01570D	REVISION: B	
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Figure 2. Package outline detail E and F of QFP100GJ (SOT2045-1)

PQFP-E-100; plastic quad flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

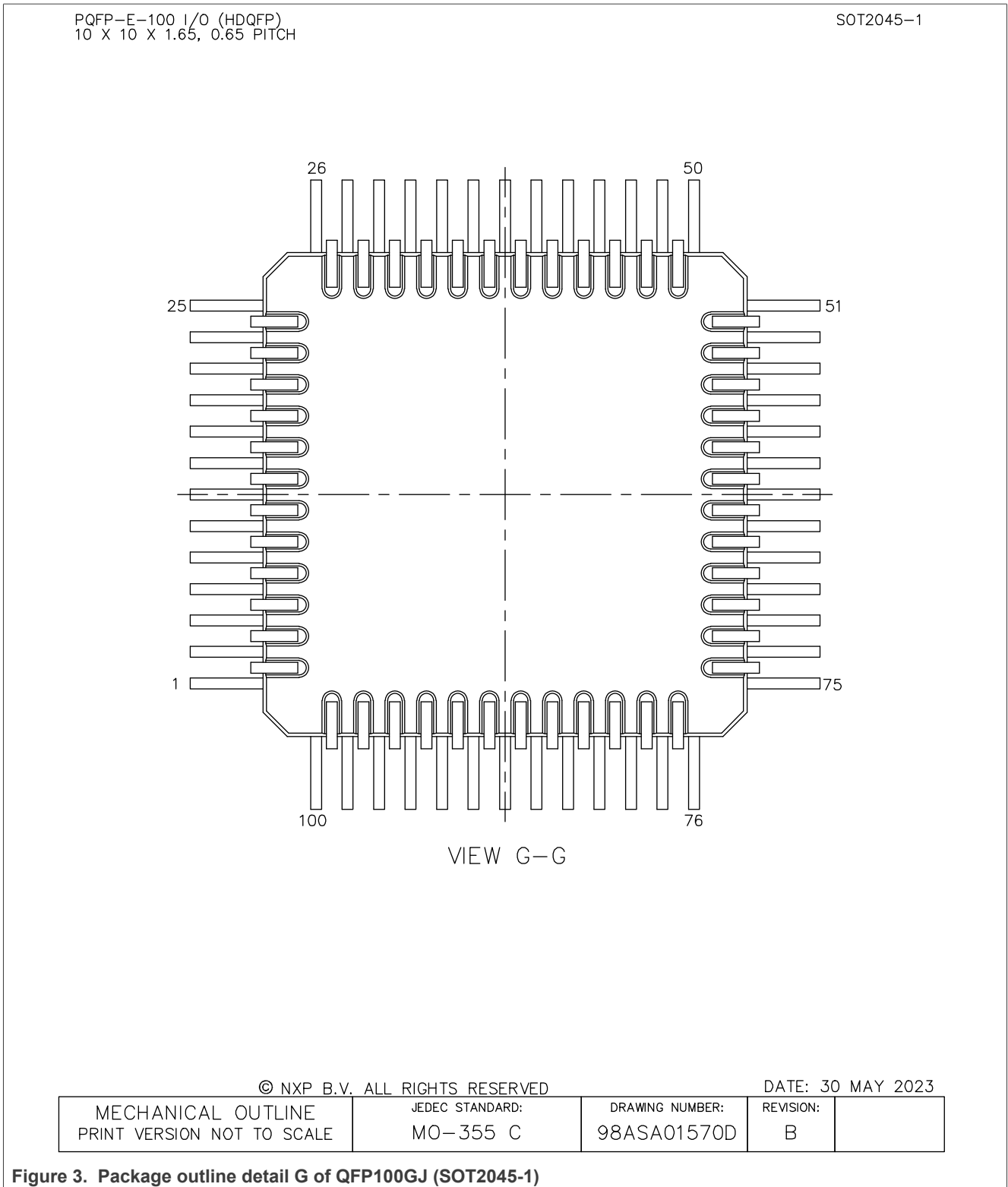
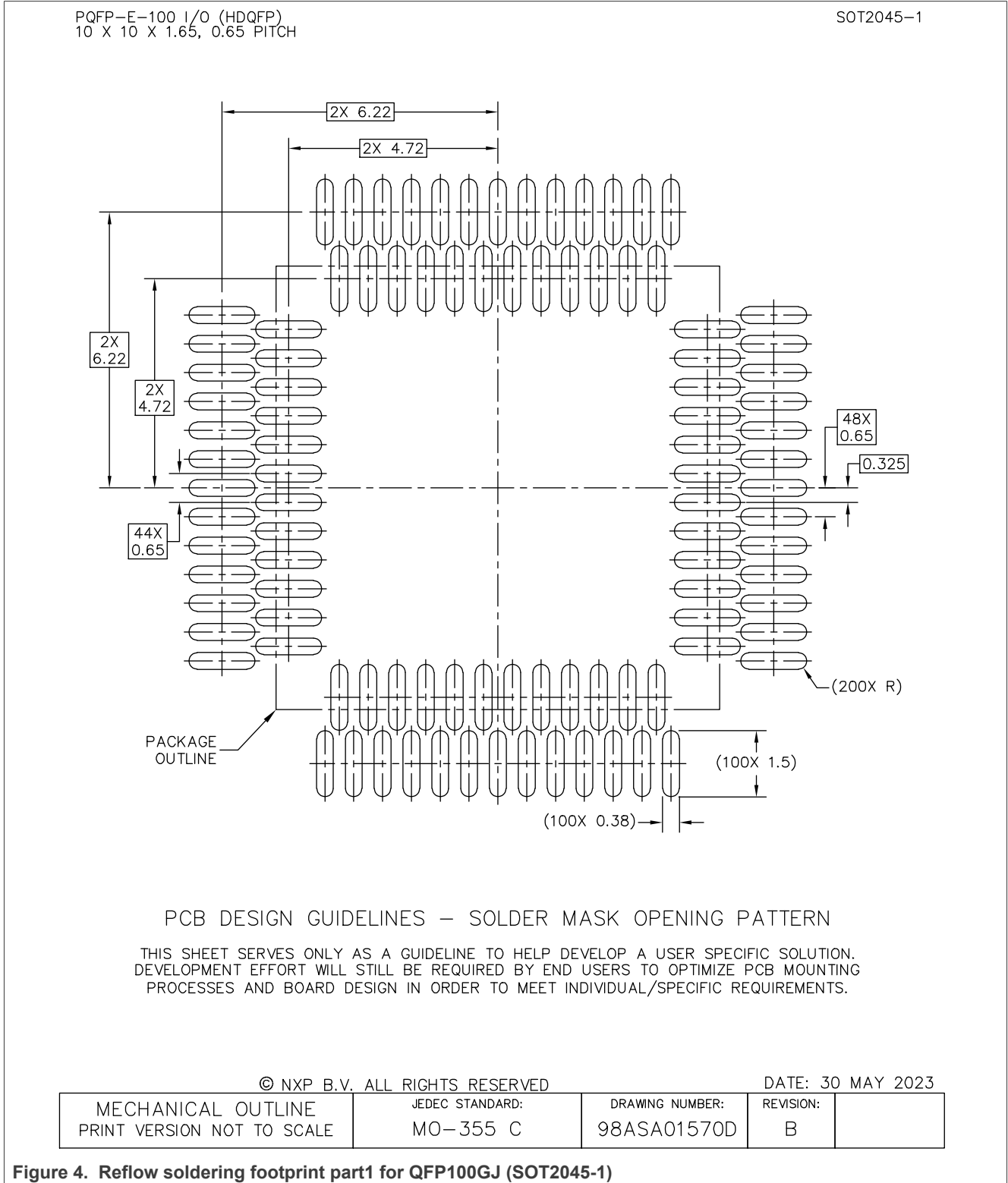


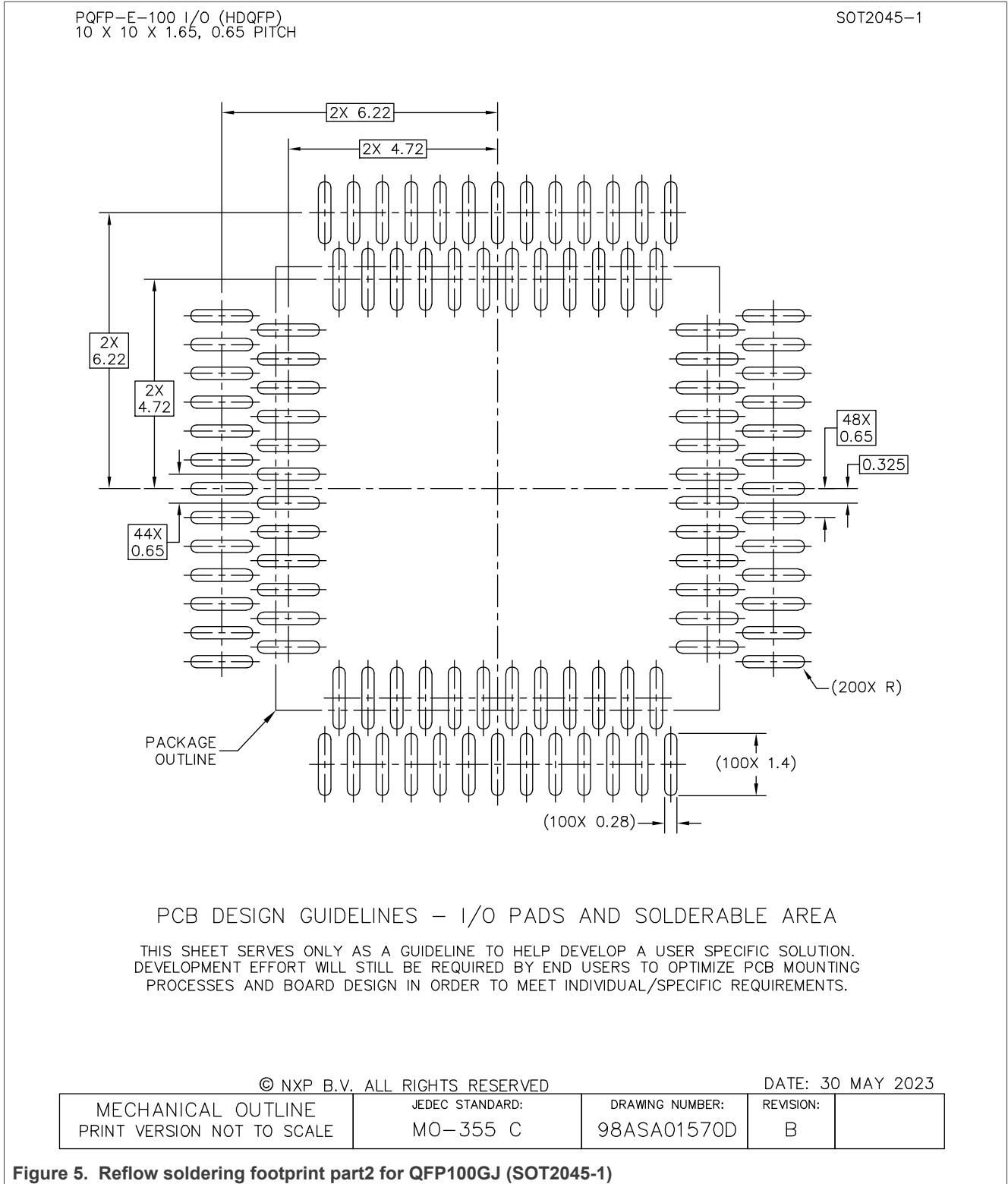
Figure 3. Package outline detail G of QFP100GJ (SOT2045-1)

PQFP-E-100; plastic qual flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

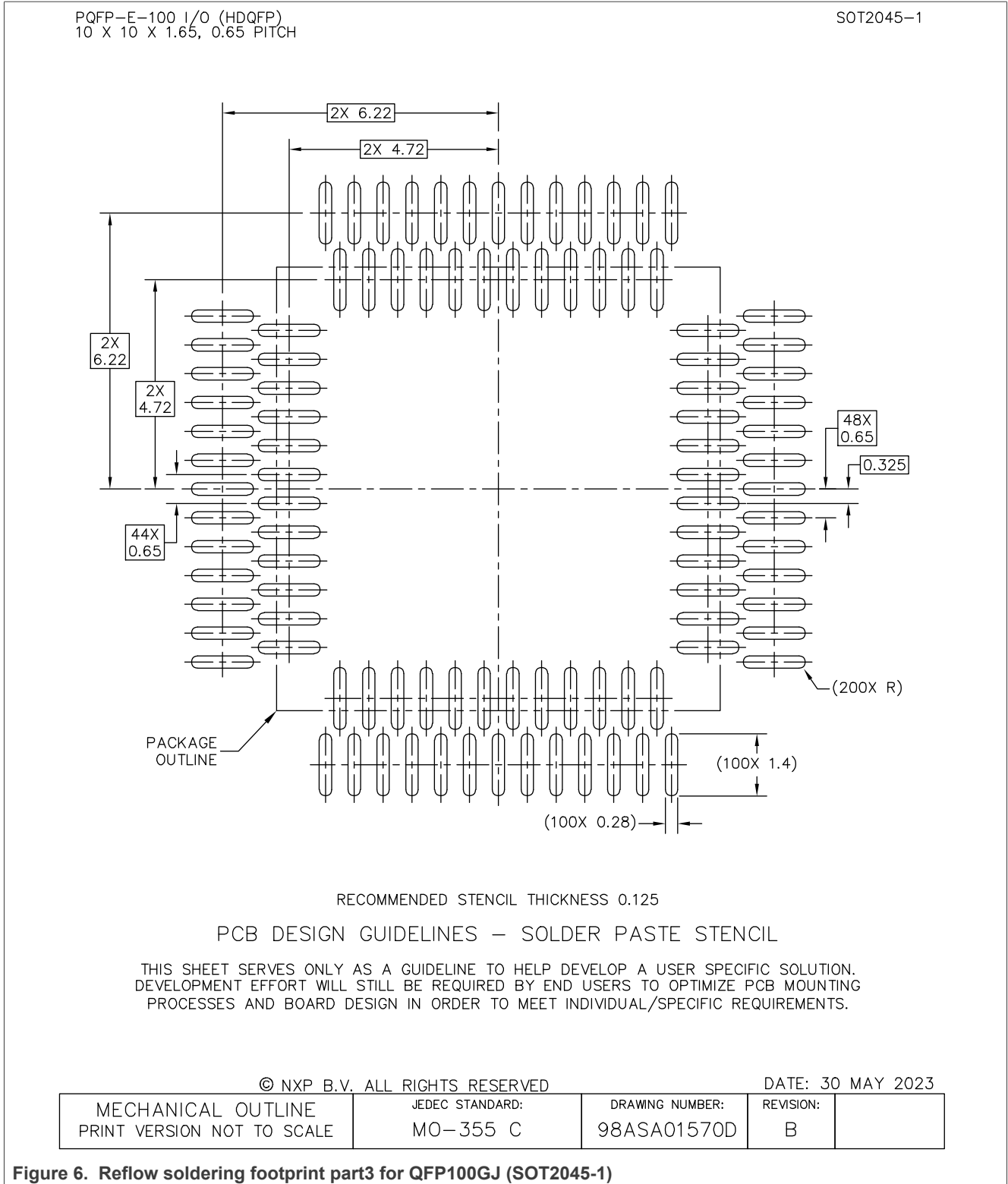
3 Soldering



PQFP-E-100; plastic qual flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.



PQFP-E-100; plastic qual flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.



PQFP-E-100; plastic quad flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

PQFP-E-100 I/O (HDQFP)  
10 X 10 X 1.65, 0.65 PITCH

SOT2045-1

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

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DATE: 30 MAY 2023

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Figure 7. Package outline note QFP100GJ (SOT2045-1)



## 4 Legal information

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PQFP-E-100; plastic quad flat package; 100 terminals, 0.65 mm pitch, 10 mm x 10 mm x 1.65 mm body size.

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